

a4

preferably the dielectric element, are flexible so that the terminals are moveable with respect to the contacts on the chip, to compensate for differential thermal expansion of the chip and substrate. The dielectric element may be provided with a compliant layer disposed between the terminals and the chip. The entire assembly is compact. --

REMARKS

The present application is a divisional of U.S. Patent Application Serial No. 08/861,280 filed May 21, 1997, and is in response to a telephonic restriction requirement of the Examiner in the '280 application. The present application is directed to the non-elected claims of the '280 parent application. The present preliminary amendment presents new claims 61 to 70, amends the title and the abstract to more accurately describe the scope of the presently claimed invention and amends the specification to correct typographical errors. The present preliminary amendment should be entered because, as set forth below, it is fully supported by the specification and introduces no new matter.

New claims 61 to 70 are directed to a semiconductor chip assembly including a semiconductor chip having contacts on the center of its top surface with a dielectric element overlying the top surface. The dielectric element has a hole which encompasses the central contacts and an edge bounding the hole. The assembly further includes a plurality of central terminals disposed on the dielectric element and a plurality of central contact leads extending from the central contacts on the chip to the central terminals. New claims 61-70 do not introduce new matter, as all of these features are set forth, *inter alia*, at page 47 and Fig. 18 of the present specification. For example, the specification uses the term "dielectric element" synonymously with the term "interposer" (specification, page 7, lines 23-28), and the new claims use the

96

A

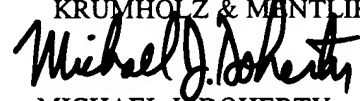
08984615 120397

term "dielectric elements" rather than "interposer" for greater clarity. In addition, the specification supports the recitation in new claim 62 that "the terminal end of each said central contact lead is integrally formed with one of said central terminals." (specification, page 19, lines 36 et seq.) Moreover, in commonly assigned parent Application Serial No. 07/673,020 (now United States Patent 5,148,265), Applicants presented claims reciting features similar to those recited herein; see, e.g., claims of the '265 patent reciting central terminals.

For all of the reasons set forth above, prompt and favorable consideration of the amended application, and allowance of new claims 61-70, is respectfully requested.

Respectfully Submitted,

LERNER, DAVID, LITTENBERG,
KRUMHOLZ & MENTLIK



MICHAEL J. DOHERTY
Reg. No. 40,592

600 South Avenue West
Westfield, New Jersey 07090
(908) 654-5000

F:\DOCS\1\MJD\3.3\122285.DOC